Claims

1. Method of processing a solder masked carrier with electronic components, comprising the method steps:

A) detecting at least one carrier related reference;

B) processing the at least one detected carrier related reference into a position of the carrier;

C) detecting a least one solder mask dependent reference;

D) processing the at least one detected solder mask dependent reference into a position of the solder mask on the carrier; and

E) processing the solder masked carrier with electronic components dependent on at least the position of the solder mask on the carrier

characterized in that the processing of the solder masked carrier with electronic components according step E) comprises the separation of the solder masked electronic components.

2. Method as claimed in claim 1, **characterized in that** the separation of the solder masked electronic components comprises the sawing of the solder masked carrier with electronic components.

3. Method as claimed in claim 1 or 2, **characterized in that** the processing steps A) and C) are combined in a single detection step.

4. Method as claimed in any of the foregoing claims, **characterized in that** the solder mask is applied to the carrier before the processing steps A) – E) take place.

5. Method as claimed in any of the foregoing claims, **characterized in that** a functional board part is detected as a carrier related reference.

6. Method as claimed in any of the foregoing claims, **characterized in that** the method also comprises the method step of attaching contacts to the solder masked carrier.

7. Method as claimed in any of the foregoing claims, **characterized in that** the processing of the solder masked carrier with electronic components according step E) involves the at least partial electronic isolation of the electronic components.

8. Method as claimed in any of the foregoing claims, **characterized in that** the processing of the solder masked carrier with electronic components according step E) is steered dependent on the processed position of the solder mask on the carrier according step D).

9. Method as claimed in any of the foregoing claims, **characterized in that** in subsequent manipulations of the processing of the solder masked carrier with electronic components according step E) new carrier and/or solder mask dependent references are detected.

10. Method as claimed in any of the foregoing claims, **characterized in that** during detection of a least one solder mask dependent reference the solder masked carrier is lighted with co-axial light.

11. Electronic component as produced with the method of any of the foregoing claims.

Claims

1. Method of processing a solder masked carrier with electronic components, comprising the method steps:

A) detecting at least one carrier related reference;

B) processing the at least one detected carrier related reference into a position of the carrier;

C) detecting a least one solder mask dependent reference; and

D) processing the at least one detected solder mask dependent reference into a position of the solder mask on the carrier,

characterized in that,

- the method further comprises the method step of E) processing the solder masked carrier with electronic components dependent on at least the position of the solder mask (as such) on the carrier; and

the processing of the solder masked carrier with electronic components according step E) comprises the separation of the solder masked electronic components.

2. Method as claimed in claim 1, **characterized in that** the separation of the solder masked electronic components comprises the sawing of the solder masked carrier with electronic components.

3. Method as claimed in claim 1 or 2, **characterized in that** the processing steps A) and C) are combined in a single detection step.

4. Method as claimed in any of the foregoing claims, **characterized in that** the solder mask is applied to the carrier before the processing steps A) – E) take place.

5. Method as claimed in any of the foregoing claims, **characterized in that** a functional board part is detected as a carrier related reference.

6. Method as claimed in any of the foregoing claims, **characterized in that** the method also comprises the method step of attaching contacts to the solder masked carrier.

7. Method as claimed in any of the foregoing claims, **characterized in that** the processing of the solder masked carrier with electronic components according step E) involves the at least partial electronic isolation of the electronic components.

8. Method as claimed in any of the foregoing claims, **characterized in that** the processing of the solder masked carrier with electronic components according step E) is steered dependent on the processed position of the solder mask on the carrier according step D).

9. Method as claimed in any of the foregoing claims, **characterized in that** in subsequent manipulations of the processing of the solder masked carrier with electronic components according step E) new carrier and/or solder mask dependent references are detected.

10. Method as claimed in any of the foregoing claims, **characterized in that** during detection of a least one solder mask dependent reference the solder masked carrier is lighted with co-axial light.